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June 1999 Revised December 2013

74VCX245

Low Voltage Bidirectional Transceiver with 3.6V Tolerant Inputs and Outputs

General Description

The VCX245 contains eight non-inverting bidirectional buffers with 3-STATE outputs and is intended for bus oriented applications. The T/\overline{R} input determines the direction of data flow. The \overline{OE} input disables both the A and B ports by placing them in a high impedance state.

The 74VCX245 is designed for low voltage (1.4V to 3.6V) $\rm V_{CC}$ applications with I/O compatibility up to 3.6V.

The 74VCX245 is fabricated with an advanced CMOS technology to achieve high-speed operation while maintaining low CMOS power dissipation.

Features

- 1.4V to 3.6V V_{CC} supply operation
- 3.6V tolerant inputs and outputs
- Power-off high impedance inputs and outputs
- Supports Live Insertion and Withdrawal (Note 1)
- t_Pr

3.5 ns max for 3.0V to 3.6V $V_{\rm CC}$

- Static Drive (I_{OH}/I_{OL}) ±24 mA @ 3.0V V_{CC}
- Uses proprietary noise/EMI reduction circuitry
- Latchup performance exceeds 300 mA
- ESD performance:

Human body model > 2000V Machine model > 200V

■ Leadless DQFN Pb-Free package

Note 1: To ensure the high impedance state during power up and power down, \overline{OE}_n should be tied to V_{CC} through a pull up resistor. The minimum value of the resistor is determined by the current sourcing capability of the driver.

Ordering Code:

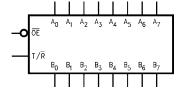
Order Number	Package Number	Package Description
74VCX245WM (Note 2)	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
74VCX245BQX (Note 3)	MLP020B	Pb-Free 20-Terminal Depopulated Quad Very-Thin Flat Pack No Leads (DQFN), JEDEC MO-241, 2.5 x 4.5mm
74VCX245MTC (Note 2)	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

Pb-Free package per JEDEC J-STD-020B.

Note 2: Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

Note 3: DQFN package available in Tape and Reel only,

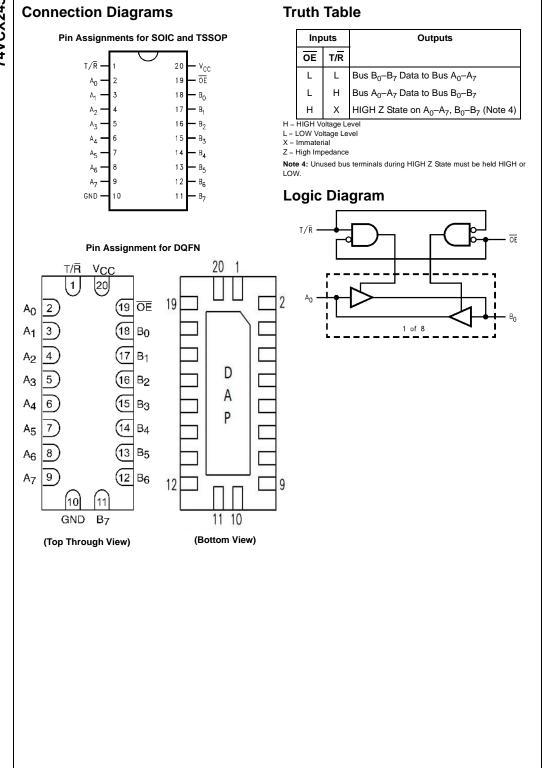
Logic Symbol



Pin Descriptions

Description
Output Enable Input (Active LOW)
Transmit/Receive Input
Side A Inputs or 3-STATE Outputs
Side B Inputs or 3-STATE Outputs
No Connect

Note: DAP (Die Attach Pad)



Absolute Maximum Ratings(Note 5)

 $\label{eq:supply Voltage VCC} Supply Voltage (V_{CC}) & -0.5V to +4.6V \\ DC Input Voltage (V_I) & -0.5V to +4.6V \\ \end{array}$

DC Output Voltage (V_O)

Outputs 3-STATE -0.5V to +4.6V Outputs Active (Note 6) -0.5V to $V_{CC} + 0.5$ V

DC Input Diode Current (I_{IK}) V_I < 0V

DC Output Diode Current (I_{OK})

 $V_{O} < 0V$ -50 mA $V_{O} > V_{CC}$ +50 mA

DC Output Source/Sink Current

 (I_{OH}/I_{OL}) ±50 mA DC V_{CC} or Ground Current ±100 mA

Storage Temperature (T_{STG}) $-65^{\circ}C$ to $+150^{\circ}C$

Recommended Operating Conditions (Note 7)

Power Supply

-50 mA

 $\begin{array}{cc} \text{Operating} & \text{1.4V to 3.6V} \\ \text{Input Voltage} & -0.3V \text{ to 3.6V} \end{array}$

Output Voltage (V_O)

Output in Active States $\rm OV~to~V_{CC}$ Output in 3-STATE $\rm OV~to~3.6V$

Output Current in I_{OH}/I_{OL}

 $V_{CC} = 3.0V \text{ to } 3.6V \\ \pm 24 \text{ mA}$

 V_{CC} = 2.3V to 2.7V \pm 18 mA V_{CC} = 1.65V to 2.3V \pm 6 mA

 V_{CC} = 1.4V to 1.6V ± 2 mA Free Air Operating Temperature (T_A) -40° C to $+85^{\circ}$ C

Minimum Input Edge Rate ($\Delta t/\Delta V$)

 $V_{IN} = 0.8V \text{ to } 2.0V, V_{CC} = 3.0V$ 10 ns/V

Note 5: The Absolute Maximum Ratings are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the Absolute Maximum Ratings. The "Recommended Operating Conditions" table will define the conditions for actual device operation.

Note 6: IO Absolute Maximum Rating must be observed.

Note 7: Floating or unused inputs must be held HIGH or LOW.

DC Electrical Characteristics

Symbol	Parameter	Conditions	V _{CC}	Min	Max	Units
			(V)			
V_{IH}	HIGH Level Input Voltage		2.7 to 3.6	2.0		
			2.3 to 2.7	1.6		V
			1.65 to 2.3	0.65 × V _{CC}		•
			1.4 to 1.6	$0.65 \times V_{CC}$		
V _{IL}	LOW Level Input Voltage		2.7 to 3.6		0.8	
			2.3 to 2.7		0.7	.,
			1.65 to 2.3		0.35 × V _{CC}	V
			1.4 to 1.6		$0.35 \times V_{CC}$	
V _{OH}	HIGH Level Output Voltage	I _{OH} = -100 μA	2.7 to 3.6	V _{CC} - 0.2		
		I _{OH} = -12 mA	2.7	2.2		
		I _{OH} = -18 mA	3.0	2.4		
		I _{OH} = -24 mA	3.0	2.2		
		$I_{OH} = -100 \mu A$	2.3 to 2.7	V _{CC} - 0.2		,
		I _{OH} = -6 mA	2.3	2.0		V
		I _{OH} = -12 mA	2.3	1.8		V
		I _{OH} = -18 mA	2.3	1.7		
		I _{OH} = -100 μA	1.65 to 2.3	V _{CC} - 0.2		,
		I _{OH} = -6 mA	1.65	1.25		
		$I_{OH} = -100 \mu A$	1.4 to 1.6	V _{CC} - 0.2		,
		I _{OH} = -2 mA	1.4	1.05		

DC Electrical Characteristics (Continued)

Symbol	Parameter	Conditions	V _{CC}	Min	Max	Units
	1000	1 100 1	(V)		2.2	
V _{OL}	LOW Level Output Voltage	$I_{OL} = 100 \mu A$	2.7 to 3.6		0.2	
		I _{OL} = 12 mA	2.7		0.4	
		I _{OL} = 18 mA	3.0		0.4	
		I _{OL} = 24 mA	3.0		0.55	
		I _{OL} = 100 μA	2.3 to 2.7		0.2	
		I _{OL} = 12 mA	2.3		0.4	V
		I _{OL} = 18 mA	2.3		0.6	
		I _{OL} = 100 μA	1.65 to 2.3		0.2	
		I _{OL} = 6 mA	1.65		0.3	
		I _{OL} = 100 μA	1.4 to 1.6		0.2	
		I _{OL} = 2 mA	1.4		0.35	
I	Input Leakage Current	$0 \le V_I \le 3.6V$	1.4 to 3.6		±5.0	μΑ
l _{OZ}	3-STATE Output Leakage	$0 \le V_O \le 3.6V$	1 140 2 0		140	^
		$V_I = V_{IH}$ or V_{IL}	1.4 to 3.6		±10	μА
l _{OFF} I	Power-OFF Leakage Current	$0 \leq (V_I, V_O) \leq 3.6V$	0		10	μА
I _{CC}	Quiescent Supply Current	V _I = V _{CC} or GND	1.4 to 3.6		20	^
		$V_{CC} \le (V_I, V_O) \le 3.6V \text{ (Note 8)}$	1.4 to 3.6		±20	μА
Δl _{CC}	Increase in I _{CC} per Input	V _{IH} = V _{CC} -0.6V	2.7 to 3.6		750	μА

Note 8: Outputs disabled or 3-STATE only.

AC Electrical Characteristics (Note 9)

Symbol	Parameter	Conditions	V _{cc}	$T_A = -40^\circ$	C to +85°C	Units	Figure
- Cymbol	T drumeter	Conditions	(V)	Min	Max	Oillio	Number
t _{PHL} , t _{PLH}	Propagation Delay	$C_L = 30 \text{ pF}, R_L = 500\Omega$	3.3 ± 0.3	0.6	3.5		
	A_n to B_n or B_n to A_n		2.5 ± 0.2	8.0	4.2		Figures 1, 2
			1.8 ± 0.15	1.5	8.4	ns	, -
		$C_L = 15 \text{ pF}, R_L = 2k\Omega$	1.5 ± 0.1	1.0	16.8		Figures 5, 6
t _{PZL} , t _{PZH}	Output Enable Time	$C_L = 30 \text{ pF}, R_L = 500\Omega$	3.3 ± 0.3	0.6	4.5		
			2.5 ± 0.2	8.0	5.6		Figures 1, 3, 4
			1.8 ± 0.15	1.5	9.8	ns	., 0, .
		$C_L = 15 \text{ pF}, R_L = 2k\Omega$	1.5 ± 0.1	1.0	19.6		Figures 5, 7, 8
t _{PLZ} , t _{PHZ}	Output Disable Time	$C_L = 30 \text{ pF}, R_L = 500\Omega$	3.3 ± 0.3	0.6	3.6		
			2.5 ± 0.2	8.0	4.0		Figures 1, 3, 4
			1.8 ± 0.15	1.5	7.2	ns	., -, .
		$C_L = 15 \text{ pF}, R_L = 2k\Omega$	1.5 ± 0.1	1.0	14.4		Figures 5, 7, 8
t _{OSHL}	Output to Output Skew	$C_L = 30 \text{ pF}, R_L = 500\Omega$	3.3 ± 0.3		0.5		
t _{OSLH}	(Note 10)		2.5 ± 0.2		0.5	ns	
			1.8 ± 0.15		0.75		
		$C_L = 15 \text{ pF}, R_L = 2k\Omega$	1.5 ± 0.1		1.5		

Note 9: For $C_L = 50_p F$, add approximately 300 ps to the AC maximum specification.

Note 10: Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}).

Dynamic Switching Characteristics

Symbol	Parameter	Conditions	V _{CC} (V)	T _A = 25°C	Units
V _{OLP}	Quiet Output Dynamic Peak V _{OL}	$C_L = 30 \text{ pF}, V_{IH} = V_{CC}, V_{IL} = 0V$	1.8	0.3	
			2.5	0.7	V
			3.3	1.0	
V _{OLV}	Quiet Output Dynamic Valley V _{OL}	$C_L = 30 \text{ pF}, V_{IH} = V_{CC}, V_{IL} = 0V$	1.8	-0.3	
			2.5	-0.7	V
			3.3	-1.0	
V _{OHV}	Quiet Output Dynamic Valley V _{OH}	$C_L = 30 \text{ pF}, V_{IH} = V_{CC}, V_{IL} = 0V$	1.8	1.3	
			2.5	1.7	V
			3.3	2.0	

Capacitance

Symbol	Parameter	Conditions	T _A = +25°C Typical	Units
C _{IN}	Input Capacitance	V _I = 0V or V _{CC} , V _{CC} = 1.8V, 2.5V or 3.3V	6.0	pF
C _{I/O}	Input/Output Capacitance	$V_{I} = 0V \text{ or } V_{CC}, V_{CC} = 1.8V, 2.5V \text{ or } 3.3V$	7.0	pF
C _{PD}	Power Dissipation Capacitance	V_I = 0V or V_{CC} , f = 10 MHz, V_{CC} = 1.8V, 2.5V or 3.3V	20.0	pF

AC Loading and Waveforms (V $_{CC}$ 3.3V \pm 0.3V to 1.8V \pm 0.15V)

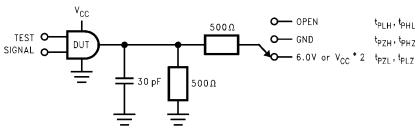


FIGURE 1. AC Test Circuit

TEST	SWITCH
t _{PLH} , t _{PHL}	Open
t _{PZL} , t _{PLZ}	6V at $V_{CC} = 3.3V \pm 0.3V$;
	V_{CC} x 2 at V_{CC} = 2.5V ± 0.2V; 1.8V ± 0.15V
t _{PZH} , t _{PHZ}	GND

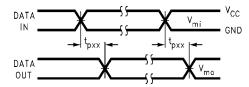


FIGURE 2. Waveform for Inverting and Non-Inverting Functions

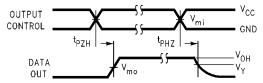


FIGURE 3. 3-STATE Output High Enable and Disable Times for Low Voltage Logic

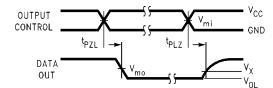
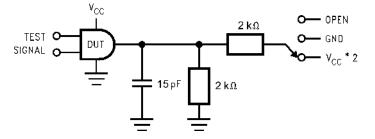


FIGURE 4. 3-STATE Output Low Enable and Disable Times for Low Voltage Logic

Symbol	V _{cc}				
Cymbol	3.3V ± 0.3V	2.5V ± 0.2V	1.8V ± 0.15V		
V _{mi}	1.5V	V _{CC} /2	V _{CC} /2		
V _{mo}	1.5V	V _{CC} /2	V _{CC} /2		
V _X	V _{OL} + 0.3V	V _{OL} + 0.15V	V _{OL} + 0.15V		
V _Y	V _{OH} – 0.3V	V _{OH} – 0.15V	V _{OH} – 0.15V		

AC Loading and Waveforms (V $_{\text{CC}}$ 1.5 \pm 0.1V)



ь ьсн		
t _{PZL}	, t _{PL}	.Z

TEST	SWITCH
$t_{\text{PLH}},t_{\text{PHL}}$	Open
t_{PZL},t_{PLZ}	V_{CC} x 2 at V_{CC} = 1.5V \pm 0.1V
t _{PZH} , t _{PHZ}	GND

FIGURE 5. AC Test Circuit

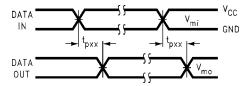


FIGURE 6. Waveform for Inverting and Non-Inverting Functions

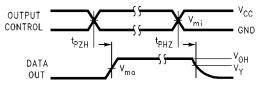


FIGURE 7. 3-STATE Output High Enable and Disable Times for Low Voltage Logic

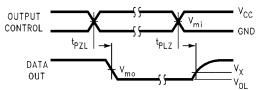


FIGURE 8. 3-STATE Output Low Enable and Disable Times for Low Voltage Logic

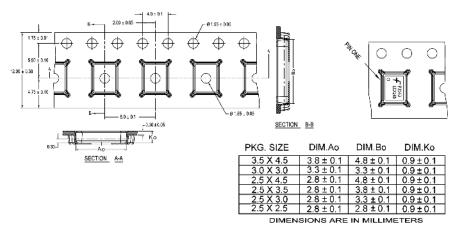
Symbol	v _{cc}
Cymbol	1.5V ± 0.1V
V_{mi}	V _{CC} /2
V_{mo}	V _{CC} /2
V_X	V _{OL} + 0.1V
V_{Y}	V _{OH} – 0.1V

Tape and Reel Specification

Tape Format for DQFN

Package	Tape	Number	Cavity	Cover Tape	
Designator	Section	Cavities	Status	Status	
	Leader (Start End)	125 (typ)	Empty	Sealed	
BQX	Carrier	3000	Filled	Sealed	
	Trailer (Hub End)	75 (typ)	Empty	Sealed	

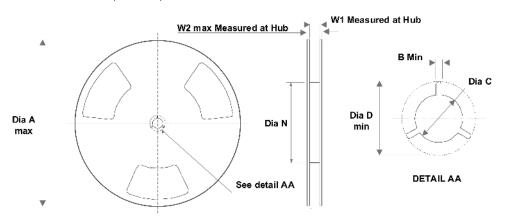
TAPE DIMENSIONS inches (millimeters)



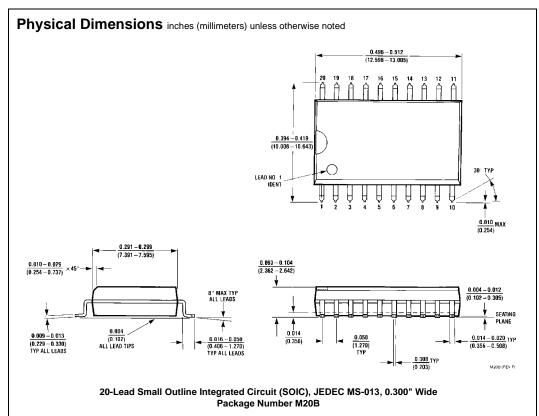
NOTES: unless otherwise specified

- 1. Cummulative pitch for feeding holes and cavities (chip pockets) not to exceed 0.008[0.20] over 10 pitch span.
- Smallest allowable bending radius.
- 3. Thru hole inside cavity is centered within cavity.
- Tolerance is ±0.002[0.05] for these dimensions on all 12mm tapes.
 Ao and Bo measured on a plane 0.120[0.30] above the bottom of the pocket.
- 6. Ko measured from a plane on the inside bottom of the pocket to the top surface of the carrier.
- Pocket position relative to sprocket hole measured as true position of pocket. Not pocket hole.
 Controlling dimension is millimeter. Diemension in inches rounded.

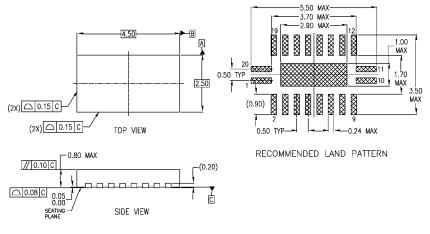
REEL DIMENSIONS inches (millimeters)

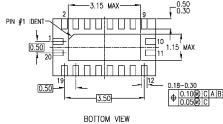


Tape Size	Α	В	С	D	N	W1	W2
12 mm	13.0	0.059	0.512	0.795	2.165	0.488	0.724
	(330.0)	(1.50)	(13.00)	(20.20)	(55.00)	(12.4)	(18.4)



Physical Dimensions inches (millimeters) unless otherwise noted (Continued)





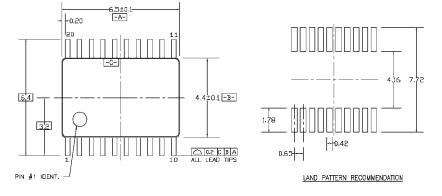
NOTES:

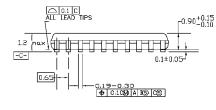
- A. CONFORMS TO JEDEC REGISTRATION MO-241, VARIATION AC
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994

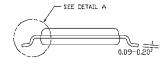
MLP020BrevA

Pb-Free 20-Terminal Depopulated Quad Very-Thin Flat Pack No Leads (DQFN), JEDEC MO-241, 2.5 x 4.5mm Package Number MLP020B

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)







12.00*

R0.09min

GAGE PLANE

DIMENSIONS ARE IN MILLIMETERS

NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MD-153, VARIATION AC, REF NOTE 6, DATE 7/93.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLDS FLASH, AND THE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M. 1982.

DETAIL A

-0.6±0.:

R0.09min

MTC20REVD1

20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide Package Number MTC20

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